

Impact of Voiding on Thermal Performance of BTCs

Board Assembly

Motivation:

- Voids can reduce thermal conductivity of solder joints
- Spot overheating could impact joint reliability
- Impact of voiding on thermal performance complex

Objective:

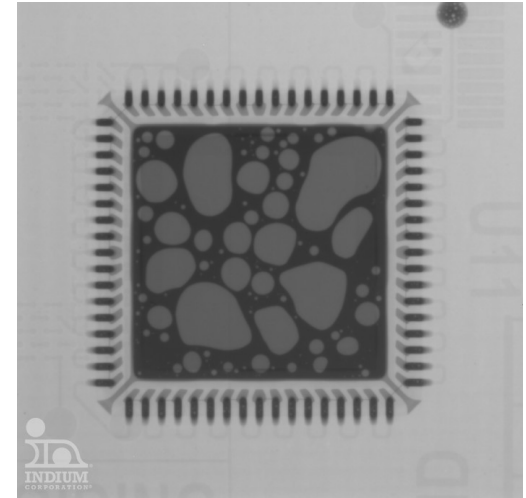
- Verify the impact and develop guidelines/design rules for acceptable voiding criteria (e.g., void density, location, size, etc.)

Strategy/Approach:

- Develop thermal measurement technique and test vehicle design
- Quantify impact of voiding on thermal performance for specific components and applications
- Engage participation from power leaders, assemblers and researchers

Longer Term:

- Updated best practices/guidelines for acceptable voiding for different package types and for range of applications
- Feed into standards efforts



Source: Indium

Status:

- Small team formulating initial project proposal / Statement of Work
- Additional early participants encouraged
- Formal Call for Participation 2Q2020
- Contact: Marks@inemi.org